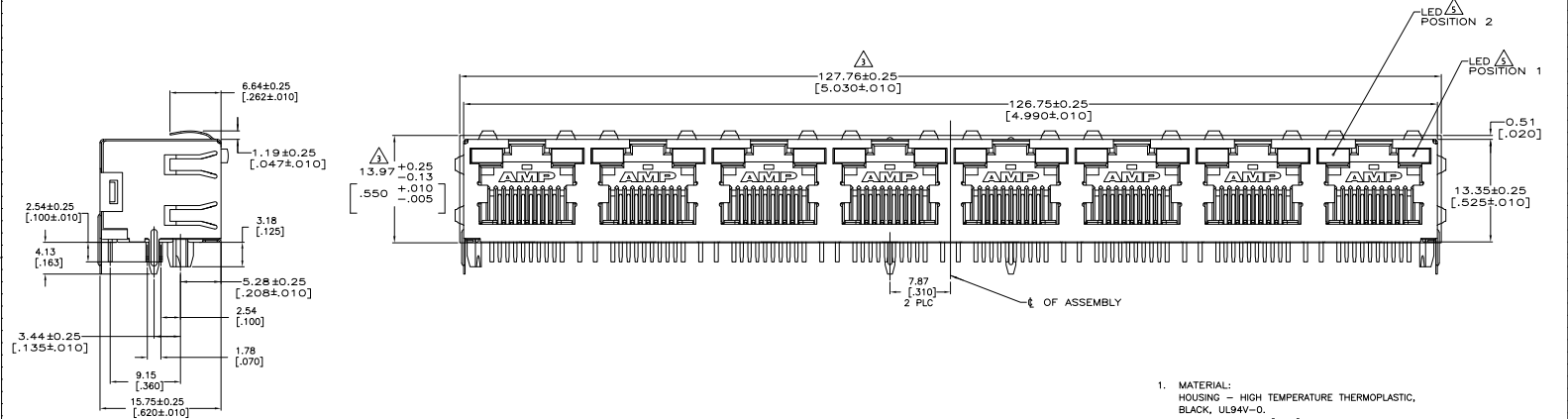


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REV	DATE	DESCRIPTION	BY	CHK	APP
AA	00				
E	02-07-020131		03NOV07	LAM	JW
ET	REVISED PER 02-08-021610		12SEP08	KK	AEG



- MATERIAL:  
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.  
 TERMINALS - 0.36[0.14] THICK PHOS BRONZE PLATED WITH 3.81µm[0.000150] MINIMUM THICK BRIGHT TIN LEAD IN SOLDER AREA. 1.27µm [0.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [0.000050] MINIMUM THICK NICKEL.  
 SHIELD - 0.196[0.077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[0.000050] MINIMUM SATIN NICKEL WITH 2.03µm[0.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.  
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[0.020 x .020] CARBON STEEL WIREFRAME LEADS: PLATED WITH 8.89µm[0.000350] TIN/COPPER OVER 2.03µm[0.000080] SILVER OVER 1.02µm[0.000040] NICKEL UNDERPLATE OVER 2.03µm[0.000080] COPPER UNDERPLATE.
  - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
  - △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
  - △ SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
  - 6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
  - △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

△	GREEN/YELLOW	GREEN/YELLOW	406556-8
△	GREEN/ORANGE	GREEN/ORANGE	406556-7
△	YELLOW	YELLOW	406556-6
△	GREEN	GREEN	406556-5
△	GREEN	YELLOW	406556-4
△	YELLOW		406556-3
△	YELLOW	GREEN	406556-2
△	YELLOW	GREEN	406556-1
	POSITION 2	POSITION 1	PART NUMBER
	INDICATOR COLOR FOR EACH HOUSING		

THIS DRAWING IS A CONTROLLED DOCUMENT.

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INVERTED MODULAR JACK ASSEMBLY, 1PK, SHIELDED, PANEL GROUND, LED

SEE NOTE 1

CUSTOMER DRAWING: 108-1163-4, 114-2154

REV: 4.1, 1 of 2, E1

